



# STB18N55M5, STD18N55M5 STF18N55M5, STP18N55M5

N-channel 550 V, 0.18  $\Omega$ , 13 A, MDmesh™ V Power MOSFET  
in D<sup>2</sup>PAK, DPAK, TO-220FP and TO-220

## Features

Order codes	V <sub>DSS</sub> @T <sub>Jmax</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>
STB18N55M5 STD18N55M5 STF18N55M5 STP18N55M5	550 V	< 0.24 $\Omega$	13 A

- DPAK worldwide best R<sub>DS(on)</sub>
- Higher V<sub>DSS</sub> rating
- High dv/dt capability
- Excellent switching performance
- Easy to drive
- 100% avalanche tested

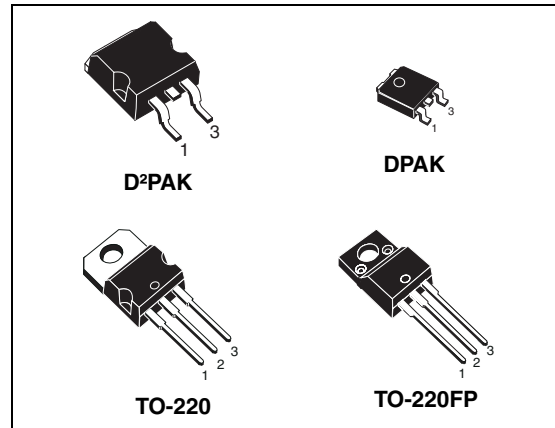
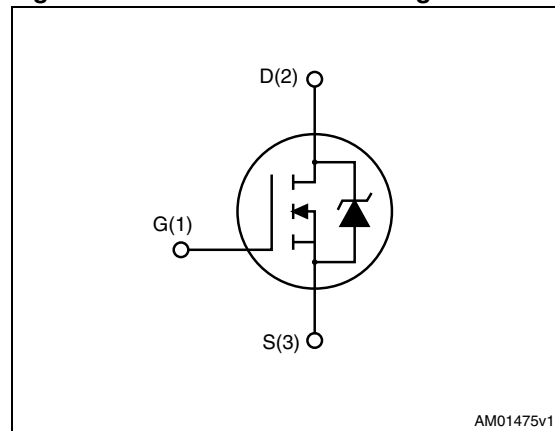


Figure 1. Internal schematic diagram



## Application

Switching applications

## Description

The devices are N-channel MDmesh™ V Power MOSFET based on an innovative proprietary vertical process technology, which is combined with STMicroelectronics' well-known PowerMESH™ horizontal layout structure. The resulting product has extremely low on-resistance, which is unmatched among silicon-based Power MOSFETs, making it especially suitable for applications which require superior power density and outstanding efficiency.

Table 1. Device summary

Order codes	Marking	Package	Packaging
STB18N55M5	18N55M5	D <sup>2</sup> PAK	Tape and reel
STD18N55M		DPAK	
STF18N55M5		TO-220FP	Tube
STP18N55M5		TO-220	

## Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		TO-220, DPAK, D <sup>2</sup> PAK	TO-220FP	
V <sub>GS</sub>	Gate-source voltage	25		V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	13	13 <sup>(1)</sup>	A
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	8.3	8.3 <sup>(1)</sup>	A
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	52	52 <sup>(1)</sup>	A
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	90	25	W
I <sub>AR</sub>	Avalanche current, repetitive or not-repetitive (pulse width limited by T <sub>j</sub> max)	4		A
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	200		mJ
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	15		V/ns
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T <sub>C</sub> = 25 °C)		2500	V
T <sub>stg</sub>	Storage temperature	- 55 to 50		°C
T <sub>j</sub>	Max. operating junction temperature	150		°C

- Limited only by maximum temperature allowed.
- Pulse width limited by safe operating area.
- I<sub>SD</sub> ≤ 13 A, di/dt ≤ 400 A/μs, V<sub>Peak</sub> < V<sub>(BR)DSS</sub>, V<sub>DD</sub> = 400 V.

**Table 3. Thermal data**

Symbol	Parameter	Value				Unit
		DPAK	D <sup>2</sup> PAK	TO-220	TO-220FP	
R <sub>thj-case</sub>	Thermal resistance junction-case max	1.39		5		°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient max			62.5		°C/W
R <sub>thj-pcb</sub>	Thermal resistance junction-pcb max	50	30			°C/W
T <sub>l</sub>	Maximum lead temperature for soldering purpose	300				°C

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 4. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$ , $V_{GS} = 0$	550			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}$ , $T_C = 125\text{ °C}$			1 100	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 25\text{ V}$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ , $I_D = 6.5\text{ A}$		0.18	0.24	$\Omega$

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0$	-	1352	-	pF
$C_{oss}$	Output capacitance			38		pF
$C_{rss}$	Reverse transfer capacitance			3.7		pF
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0\text{ to }440\text{ V}$	-	98	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related			35		pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}$ open drain	-	1.7	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 440\text{ V}$ , $I_D = 6.5\text{ A}$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 19</a> )	-	31	-	nC
$Q_{gs}$	Gate-source charge			6.3		nC
$Q_{gd}$	Gate-drain charge			14		nC

1.  $C_{DSS\text{ eq}}$  time related is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

2.  $C_{DSS\text{ eq}}$  energy related is defined as a constant equivalent capacitance giving the same stored energy as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$	Turn-off delay time	$V_{DD} = 400\text{ V}$ , $I_D = 9\text{ A}$ , $R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 18</a> , <a href="#">Figure 23</a> )		29		ns
$t_r$	Rise time		-	9.5	-	ns
$t_c$	Cross time				23	ns
$t_f$	Fall time				13	ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		13	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				52	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 13\text{ A}$ , $V_{GS} = 0$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 13\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$ (see <a href="#">Figure 20</a> )	-	238		ns
$Q_{rr}$	Reverse recovery charge			2.8		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			23.5		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 13\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$ (see <a href="#">Figure 20</a> )	-	278		ns
$Q_{rr}$	Reverse recovery charge			3.3		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current			24		A

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220, D<sup>2</sup>PAK

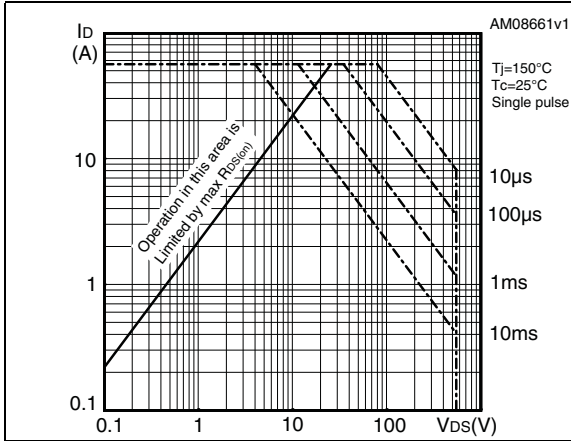


Figure 3. Thermal impedance for TO-220, D<sup>2</sup>PAK

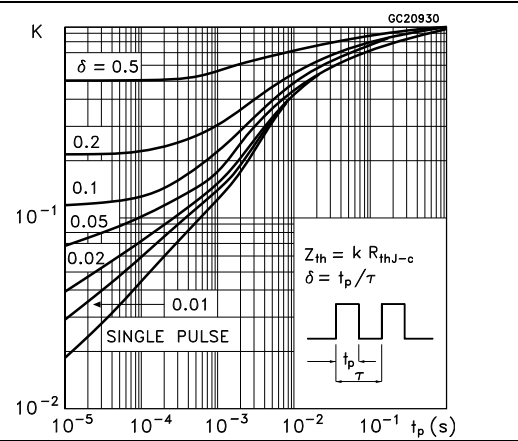


Figure 4. Safe operating area for DPAK

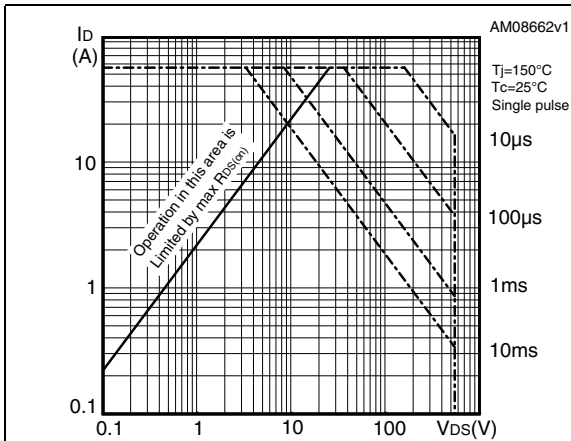


Figure 5. Thermal impedance for DPAK

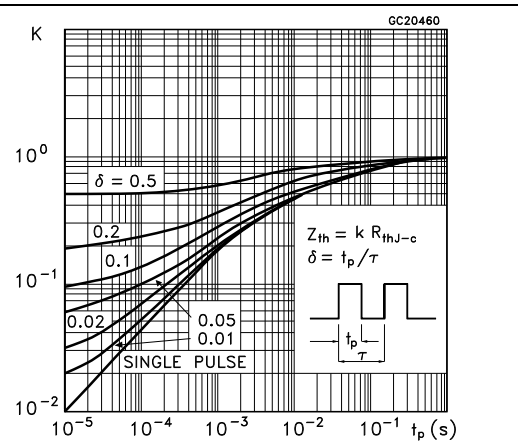


Figure 6. Safe operating area for TO-220FP

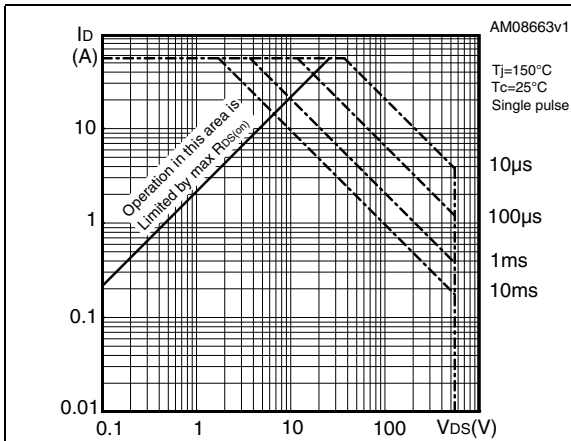


Figure 7. Thermal impedance for TO-220FP

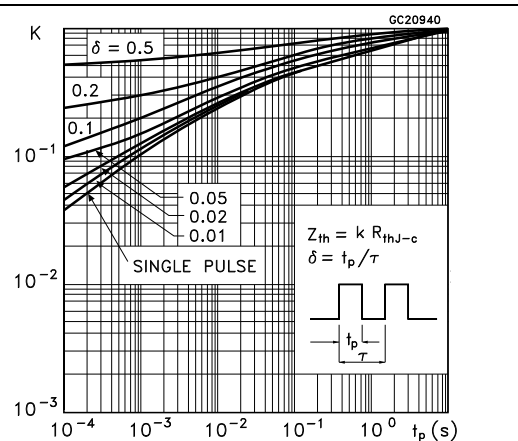


Figure 8. Output characteristics

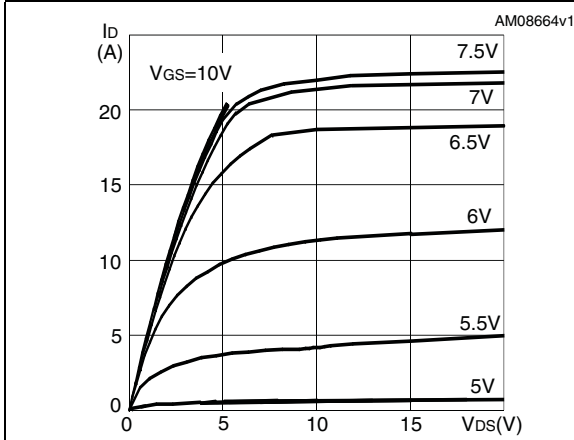


Figure 9. Transfer characteristics

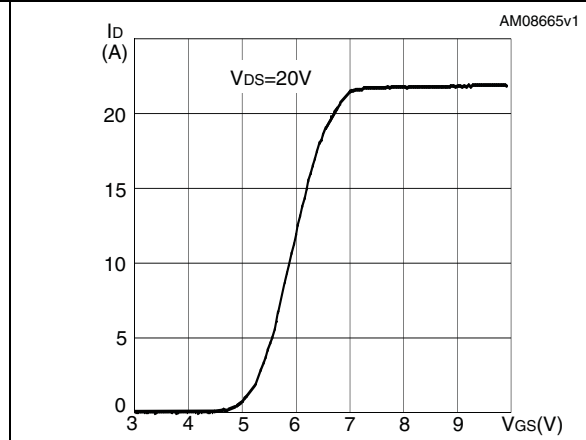


Figure 10. Gate charge vs gate-source voltage Figure 11. Static drain-source on resistance

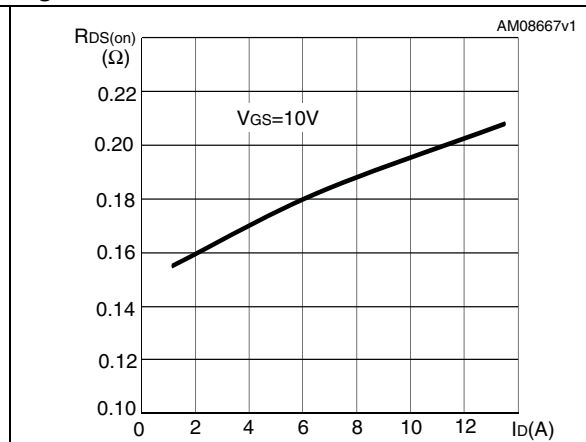
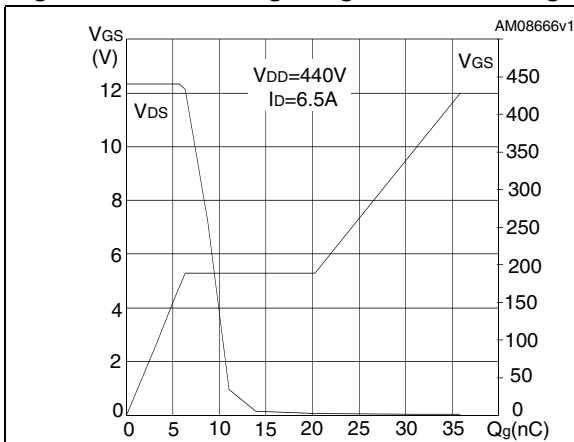


Figure 12. Capacitance variations

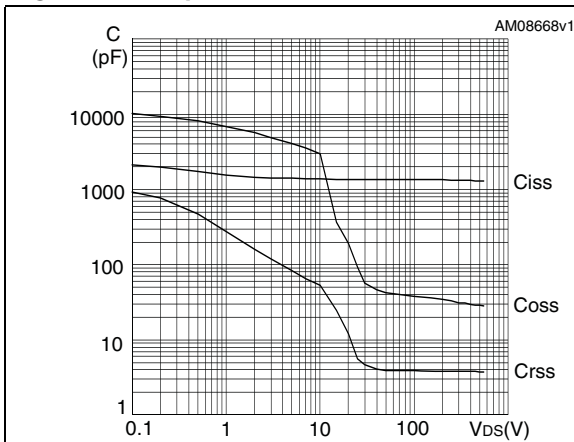


Figure 13. Output capacitance stored energy

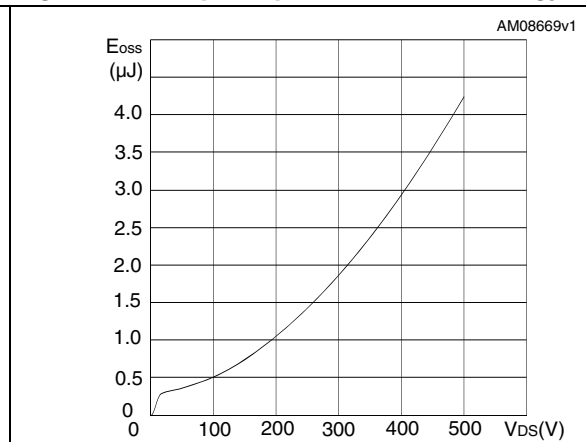


Figure 14. Normalized gate threshold voltage vs temperature

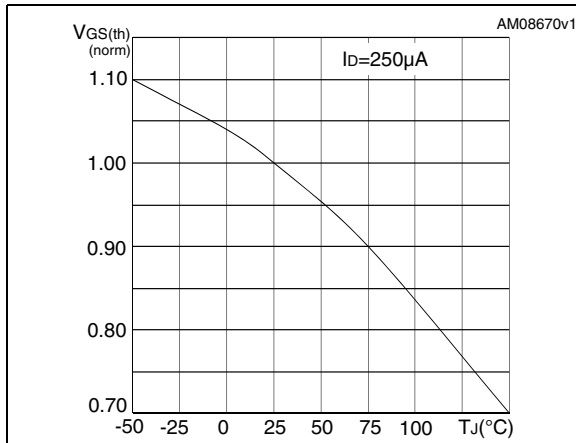


Figure 15. Normalized on resistance vs temperature

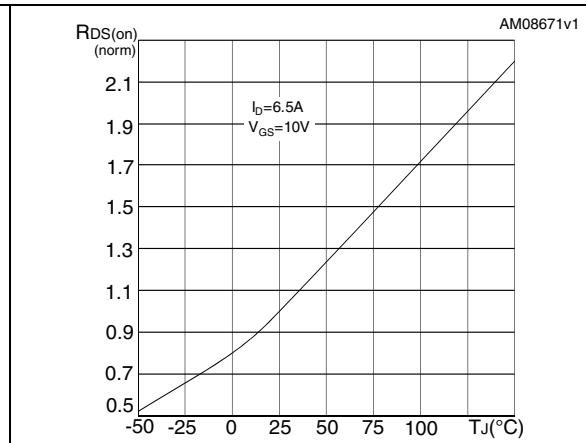


Figure 16. Switching losses vs gate resistance (1)

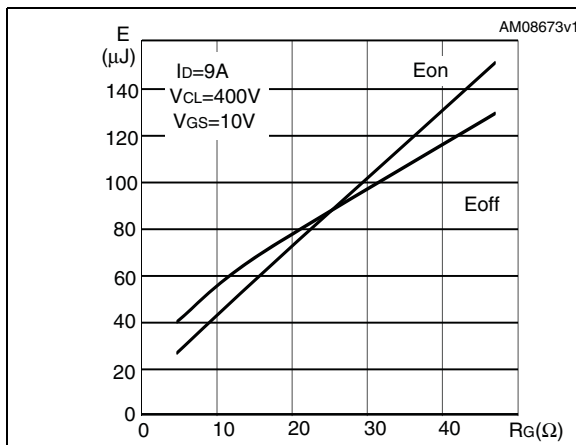
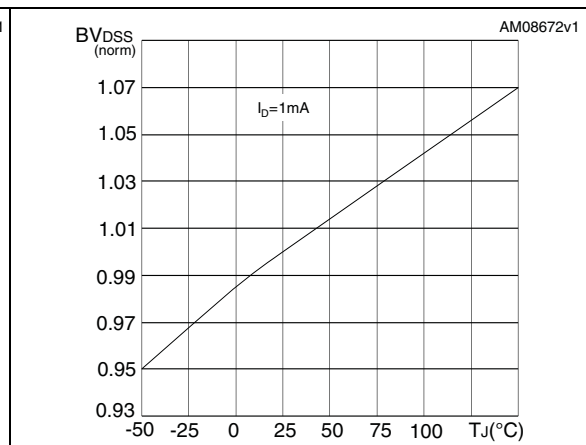


Figure 17. Normalized B<sub>V</sub>DSS vs temperature



1. Eon including reverse recovery of a SiC diode



### 3 Test circuits

Figure 18. Switching times test circuit for resistive load

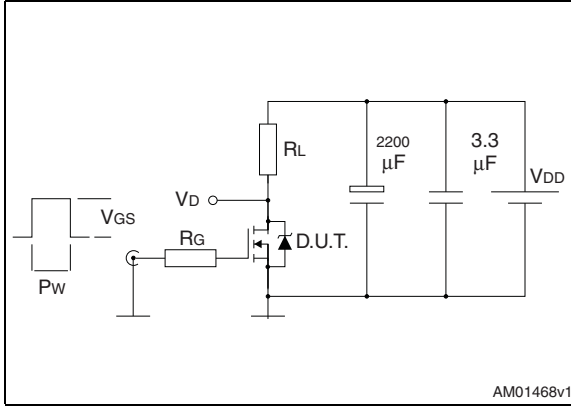


Figure 19. Gate charge test circuit

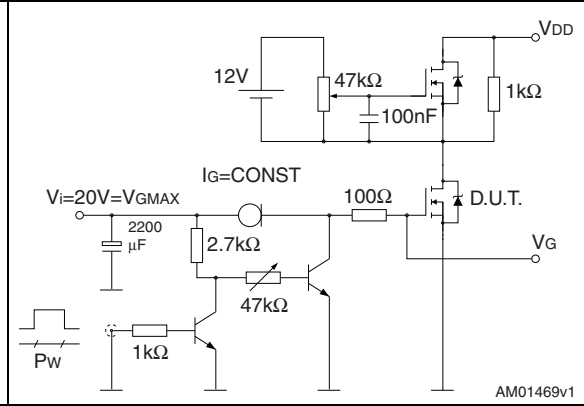


Figure 20. Test circuit for inductive load switching and diode recovery times

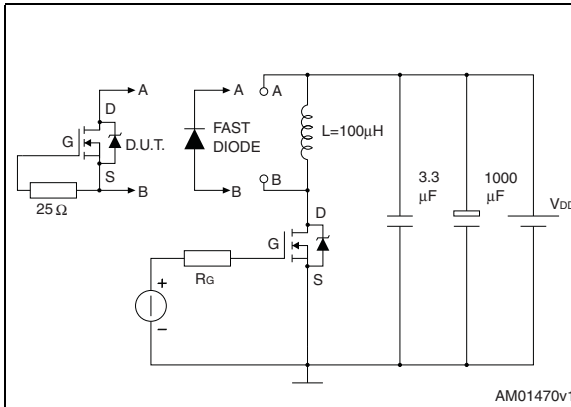


Figure 21. Unclamped inductive load test circuit

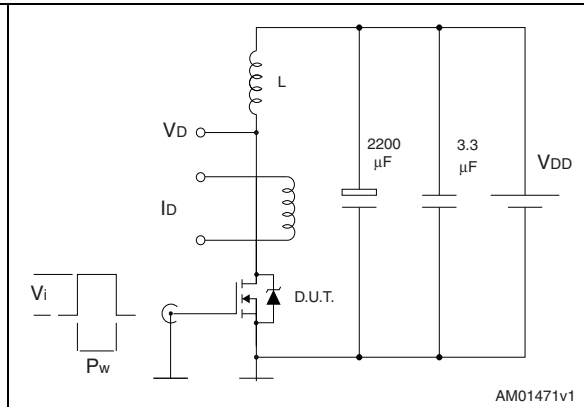


Figure 22. Unclamped inductive waveform

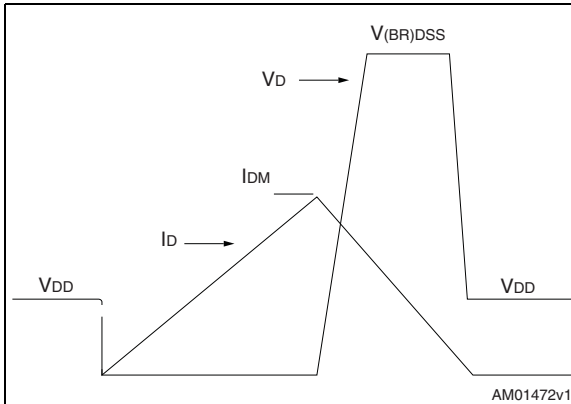
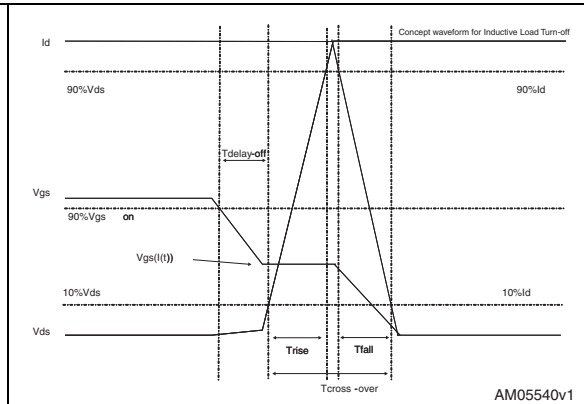


Figure 23. Switching time waveform



## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

Table 8. TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

Figure 24. TO-220FP drawing

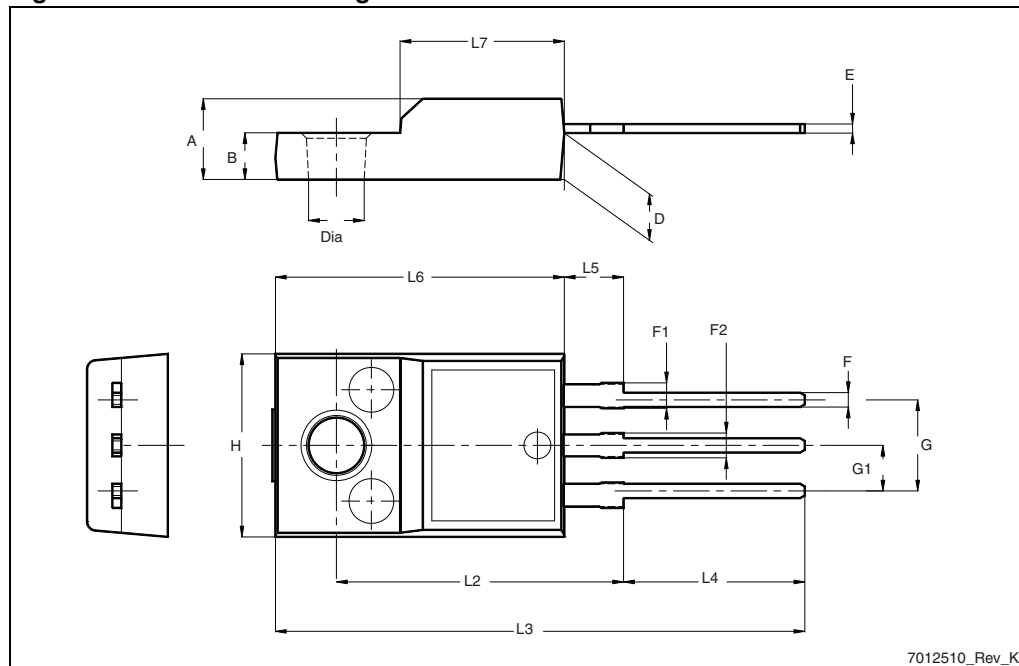
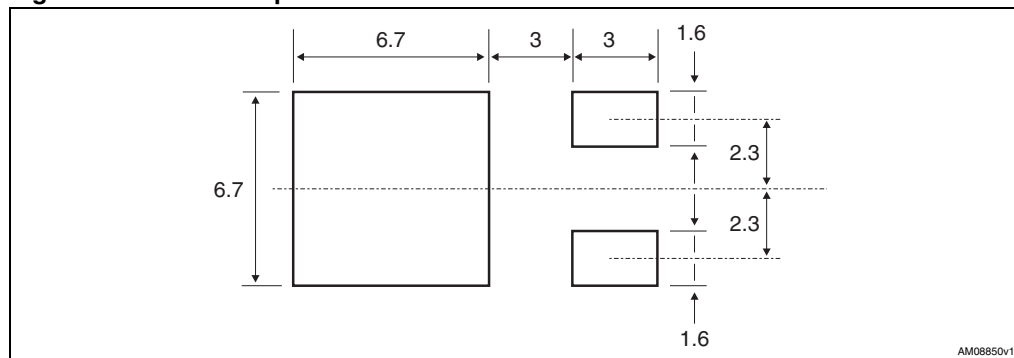


Table 9. DPAK (TO-252) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1		5.10	
E	6.40		6.60
E1		4.70	
e		2.28	
e1	4.40		4.60
H	9.35		10.10
L	1		
L1		2.80	
L2		0.80	
L4	0.60		1
R		0.20	
V2	0°		8°

Figure 25. DPAK footprint<sup>(a)</sup>



a. All dimension are in millimeters

Figure 26. DPAK (TO-252) drawing

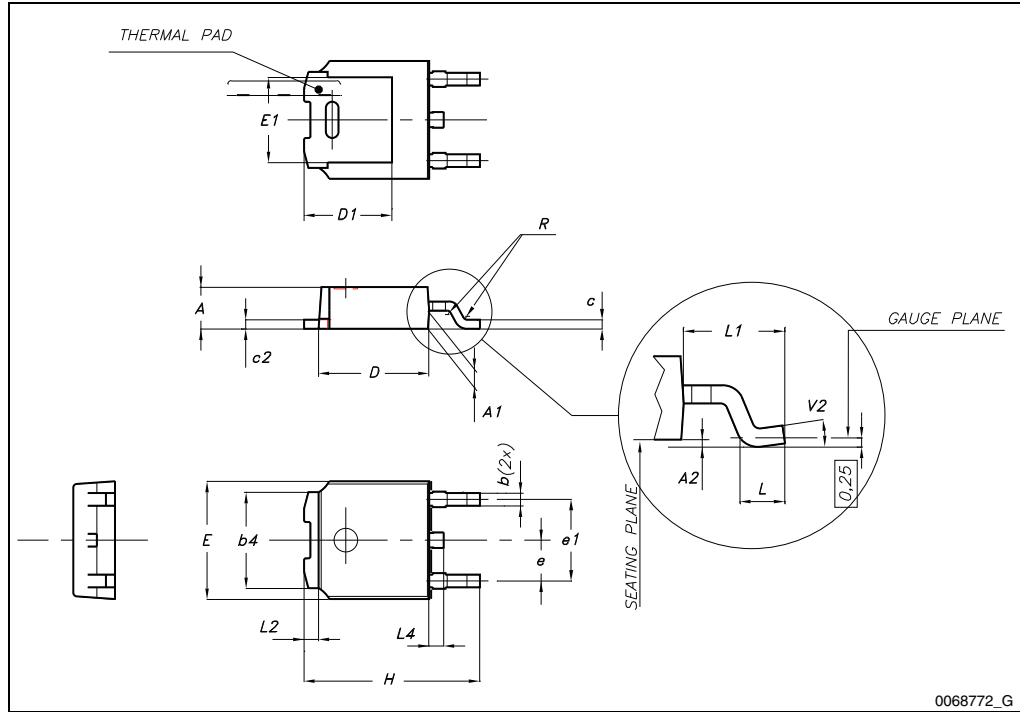


Table 10. TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Figure 27. TO-220 type A drawing

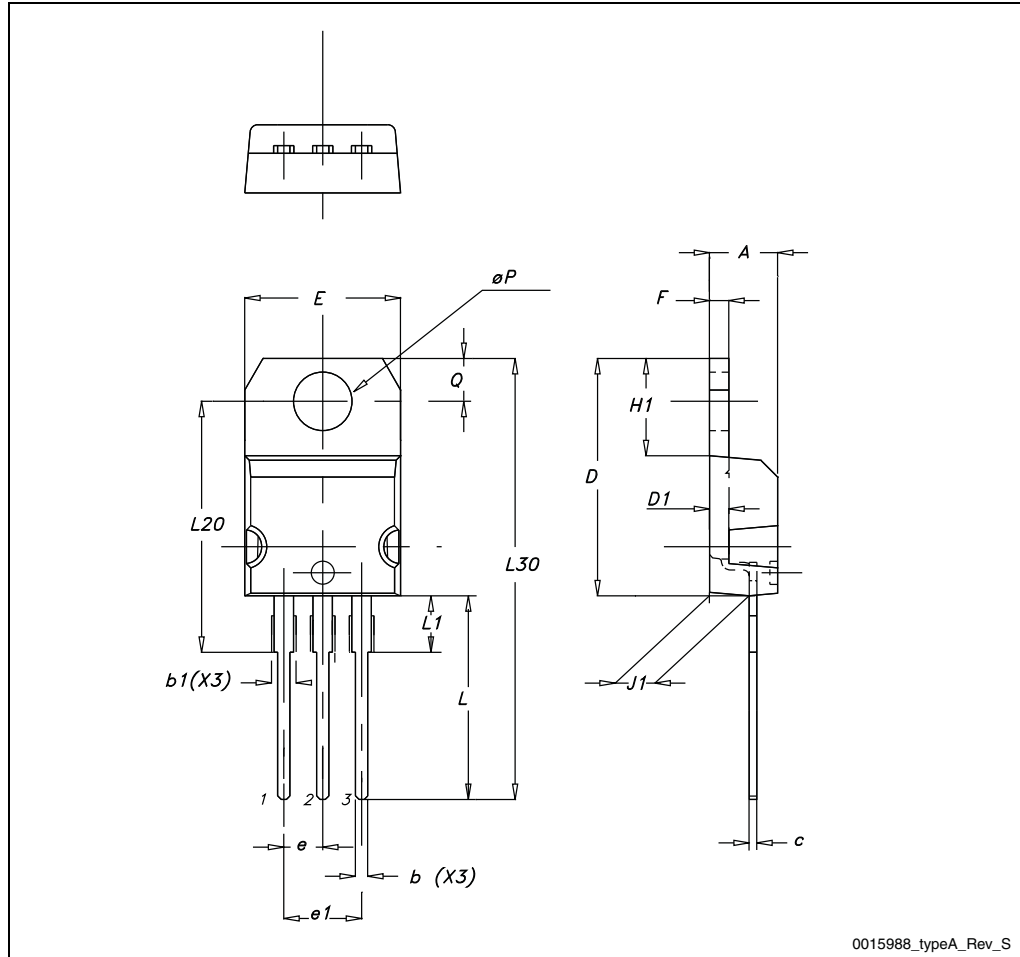


Table 11. D<sup>2</sup>PAK (TO-263) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50		
E	10		10.40
E1	8.50		
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°



Figure 28. D<sup>2</sup>PAK (TO-263) drawing

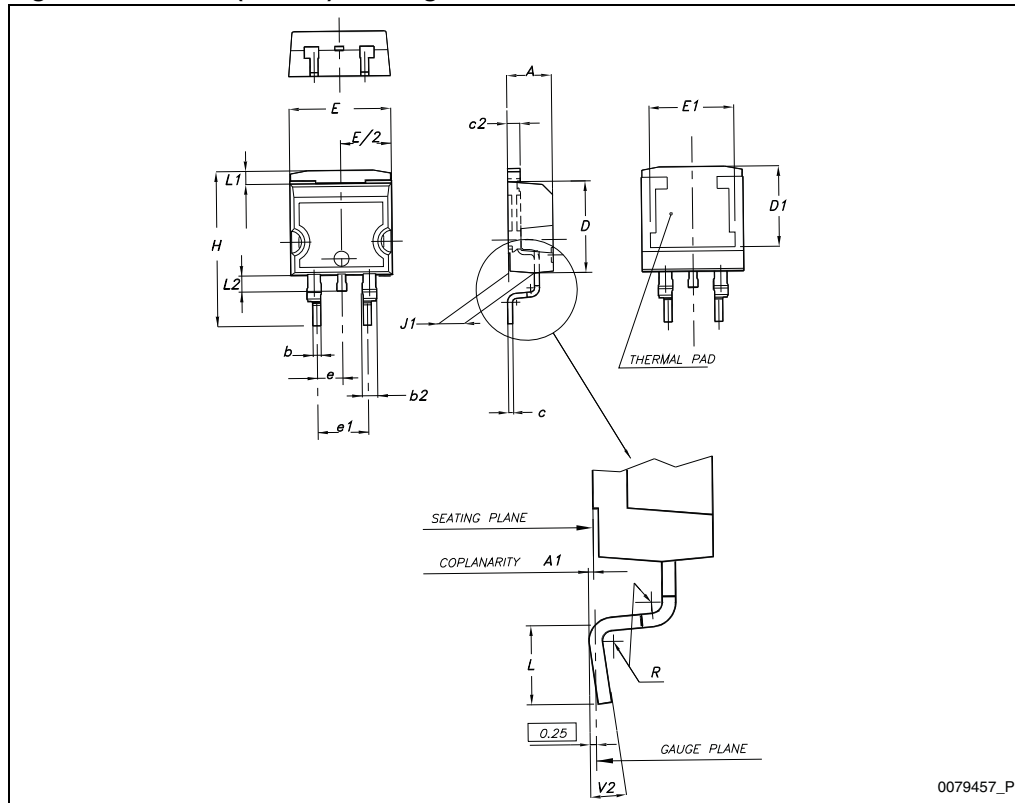
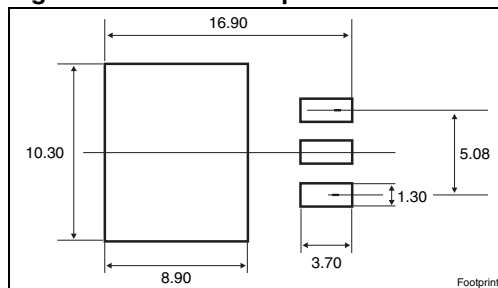


Figure 29. D<sup>2</sup>PAK footprint<sup>(b)</sup>



b. All dimension are in millimeters

## 5 Packaging mechanical data

Table 12. D<sup>2</sup>PAK (TO-263) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base qty.	1000
P2	1.9	2.1		Bulk qty.	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Table 13. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

Figure 30. Tape for DPAK and D<sup>2</sup>PAK

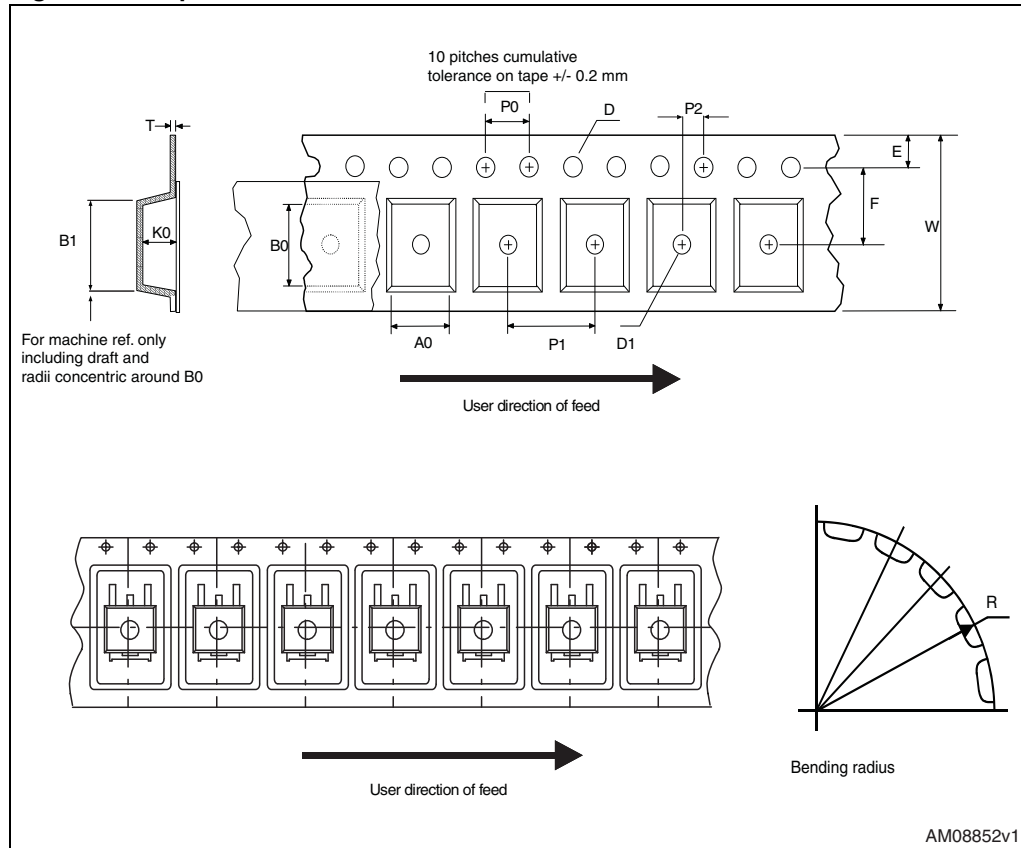
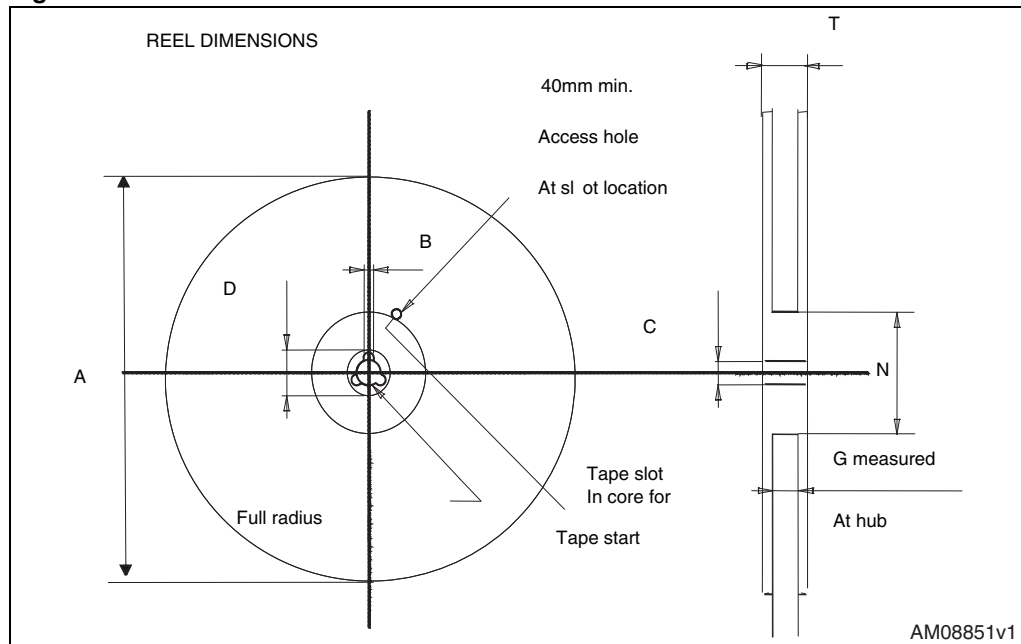


Figure 31. Reel for DPAK and D<sup>2</sup>PAK



## 6 Revision history

Table 14. Document revision history

Date	Revision	Changes
09-Feb-2010	1	First release.
04-Mar-2011	2	<ul style="list-style-type: none"><li>– Document status promoted from preliminary data to datasheet;</li><li>– Added new package, mechanical data: D<sup>2</sup>PAK.</li></ul>

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